

Amendments to the Claims:

If entered, this listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A shielded cable device comprising:
A conductor; and
a conductive shield surrounding said conductor wherein said conductive shield comprises a conductive loaded, resin-based material comprising micron
5 conductive metal powder ~~conductive materials~~ in a base resin host wherein the
ratio, by weight, of said micron conductive metal powder to said resin host is
between 0.20 and 0.40.
2. (Canceled)
3. (Canceled)
4. (Currently Amended) The device according to Claim 1 ~~3~~ wherein said metal powder is nickel, copper, silver, or is a material plated with nickel, copper, or silver.

5. (Original) The device according to Claim 3 wherein said metal powder comprises a diameter of between about 3 μm and about 12 μm .
6. (Currently Amended) The device according to Claim 1 ~~wherein said conductive materials~~ further comprising ~~comprise~~ non-metal powder.
7. (Original) The device according to Claim 6 wherein said non-metal powder is carbon, graphite, or an amine-based material.
8. (Canceled)
9. (Currently Amended) The device according to Claim 1 ~~wherein said conductive materials comprise~~ further comprising micron conductive fiber.
10. (Original) The device according to Claim 9 wherein said micron conductive fiber is nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber or combinations thereof.
11. (Original) The device according to Claim 9 wherein said micron conductive fiber pieces each have a diameter of between about 3 μm and about 12 μm and a length of between about 2 mm and about 14 mm.
12. (Canceled)

13. (Original) The device according to Claim 1 wherein said conductor comprises a wire with a surrounding insulating layer.
14. (Original) The device according to Claim 13 further comprising a metal layer overlying a part of said conductive shield.
15. (Original) The device according to Claim 13 further comprising a grounding conductor embedded in said conductive shield.
16. (Original) The device according to Claim 13 further comprising an insulating outer jacket surrounding said conductive shield.
17. (Original) The device according to Claim 16 wherein said insulating outer jacket comprises a resin-based material.
18. (Original) The device according to Claim 17 wherein said resin host of said conductive shield is the same material composition as said resin-based material of said insulating outer jacket.
19. (Original) The device according to Claim 13 further comprising at least one additional conductor wherein said additional conductor comprises a wire with a surrounding insulating layer.

20. (Original) The device according to Claim 19 wherein said conductor and said additional conductor are twisted together to form a twisted pair of signal wires.

21. (Original) The device according to Claim 20 further comprising at least one additional twisted pair of signal wires.

22. (Currently Amended) A shielded cable device comprising:

A conductor wherein said conductor comprises a wire with a surrounding insulating layer;

a conductive shield surrounding said conductor wherein

5 said conductive shield comprises a conductive loaded, resin-based material comprising micron conductive non-plated metal fiber ~~conductive materials~~ in a base resin host wherein the ratio, by weight, of said micron conductive non-plated metal fiber to said resin host is between 0.20 and 0.40; and

an insulating outer jacket surrounding said conductive shield.

23. (Canceled)

24. (Currently Amended) The device according to Claim 22 ~~wherein said conductive materials comprise~~ further comprising metal powder.

25. (Currently Amended) The device according to Claim 22 ~~wherein said~~
~~conductive materials comprise~~ further comprising non-metal powder.
26. (Currently Amended) The device according to Claim 22 ~~wherein said~~
~~conductive materials comprise~~ further comprising a combination of metal powder
and non-metal powder.
27. (Canceled)
28. (Canceled)
29. (Original) The device according to Claim 22 further comprising a metal layer
overlying a part of said conductive shield.
30. (Original) The device according to Claim 22 further comprising a grounding
conductor embedded in said conductive shield.
31. (Original) The device according to Claim 22 wherein said insulating outer
jacket comprises a resin-based material.
32. (Original) The device according to Claim 22 further comprising at least one
additional conductor wherein said additional conductor comprises a wire with a
surrounding insulating layer.

33. (Original) The device according to Claim 32 wherein said conductor and said additional conductor are twisted together to form a twisted pair of signal wires.

34. (Original) The device according to Claim 33 further comprising at least one additional twisted pair of signal wires.

35. (Currently Amended) A method to form a shielded cable device, said method comprising:

~~providing a conductor; and~~

~~forming a conductive shield surrounding said conductor wherein said~~

5 ~~conductive shield comprises a conductive loaded, resin-based material further comprising conductive materials in a resin host~~

~~pulling said conductor;~~

~~extruding a conductive loaded, resin-based material onto a conductor to~~

~~thereby form a conductive shield on said conductor wherein said conductive~~

10 ~~loaded, resin-based material comprises micron conductive non-plated metal fiber and wherein the ratio, by weight, of said conductive materials to said resin host is between 0.20 and 0.40; and~~

~~curing said conductive loaded, resin-based material.~~

36. (Canceled)

37. (Currently Amended) The method according to Claim 35 ~~wherein the~~
~~conductive materials comprise~~ further comprising a conductive powder.
38. (Canceled)
39. (Canceled) .
40. (Canceled)
41. (Currently Amended) The method according to Claim 35 ~~40~~ further
comprising extruding an insulating outer jacket onto said conductive shield.
42. (Canceled)
43. (Canceled)
44. (Original) The method according to Claim 35 further comprising forming a
metal layer overlying a part of said conductive shield.
45. (Original) The method according to Claim 44 wherein said step of forming a
metal layer around said conductive loaded, resin-based material is by plating or
by coating said metal layer.